504446343 07/07/2017

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT4493044

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YOICHIRO KURITA	05/07/2015

RECEIVING PARTY DATA

Name:	KABUSHIKI KAISHA TOSHIBA
Street Address:	1-1, SHIBAURA 1-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
Postal Code:	105-8001

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15643623

CORRESPONDENCE DATA

Fax Number: (212)319-5101

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2123194900

Email: aplanders@HHPATENT.COM
Correspondent Name: HOLTZ, HOLTZ & VOLEK PC

Address Line 1: 630 NINTH AVENUE

Address Line 2: SUITE 1010

Address Line 4: NEW YORK, NEW YORK 10036-3744

ATTORNEY DOCKET NUMBER:	15232C1	
NAME OF SUBMITTER:	ALLYSON PLANDERS	
SIGNATURE:	/Allyson Planders/	
DATE SIGNED:	07/07/2017	
	This document serves as an Oath/Declaration (37 CFR 1.63).	

Total Attachments: 1

source=15232C1_Declaration_Assignment#page1.tif

PATENT 504446343 REEL: 042929 FRAME: 0013

Combined Declaration and Assignment for Utility or Design Application

Title of Invention	BONDING METHOD OF SEMICONDUCTOR CHIP AND BONDING APPARATUS OF SEMICONDUCTOR CHIP				
As the belov	v named inventor, I he	reby declare that:			
is directed to:		attached application, or			
		d States application or PCT international application erfiled on			
The above-i	dentified application w	as made or authorized to be made b	y me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.					
In consideration of value received, I sell and assign to <u>Kabushiki Kaisha Toshiba</u> , having a business address at <u>1-1</u> , <u>Shibaura 1-chome Minato-ku. Tokyo 105-8001 Japan</u> , its successors, assigns or nominees, hereinafter referred to as "Assignee", my entire right, title and interest in and to said invention, and in and to all applications for patent and patents for said invention, in all countries of the world, including all divisions, reissues, continuations, substitutions and extensions thereof and all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of intellectual property, including rights of priority, resulting from the filing of any of said applications.					
I authorize said Assignee to file and prosecute an application or applications for patent for said invention as the applicant, and I request any official whose duty it is to issue patents, to issue any patent on said invention to said Assignee.					
I agree that on request and without further consideration, but at the expense of said Assignee, I will communicate to said Assignee or its representatives all facts known to me respecting said invention and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue, or other applications, make all rightful oaths and declarations, and generally do everything possible to aid said Assignee to obtain and enforce proper patent protection for said invention in all countries.					
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.					
LEGAL NAME OF INVENTOR					
Yolo	hiro KURITA	yoichiro Kwita	May 7, 2015		
Invento	r (printed name)	Signature	Date		

Holtz, Holtz, Goodman & Chick PC 220 Fifth Avenue, 16th Floor, New York, NY 10001-7708 Tel. (212) 319-4900 Fax. (212) 319-5101

> PATENT REEL: 042929 FRAME: 0014

RECORDED: 07/07/2017